

cont
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connecting the conductive pattern to the via conductor.

6. (Amended) The method of claim 4, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive pattern to the via-conductor.

9. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-conductor.

10. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered substrate; and

connecting the conductive pattern to the via-conductor.

13. (Amended) The method of claim 11, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of claim 11, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

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17. (Amended) The method of claim 15, wherein the first intaglio and the second intaglio are identical to each other.

18. (Amended) The method of claim 15, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

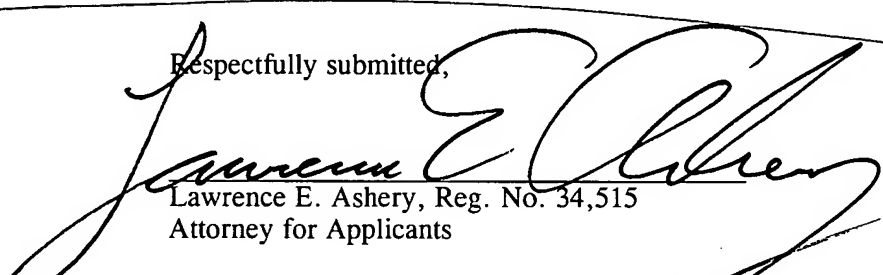
connecting at least one of the first and second conductive patterns to the first via-conductor.

19. (Amended) The method of claim 15, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.

Respectfully submitted,


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LEA/fp

Enclosure: Version With Markings Showing Changes Made

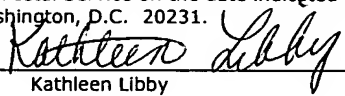
Dated: February 7, 2002

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Kathleen Libby